Supertex inc.

N-Channel Depletion-Mode Vertical DMOS FETs

Ordering Information

BV _{DSX} /	BV _{DSX} / R _{DS(ON)} I _{DSS} BV _{DGX} (max) (min)		Order Number / Package		
			TO-92	TO-243AA*	
300V	12Ω	200mA	DN2530N3	DN2530N8	

^{*} Same as SOT-89. Product shipped on 2000 piece carrier tape reels.

Product marking for TO-243AA: DN5T* Where * = 2-week alpha date code

Features

- ☐ High input impedance
- Low input capacitance
- ☐ Fast switching speeds
- Low on resistance
- ☐ Free from secondary breakdown
- Low input and output leakage

Applications

- Normally-on switches
- Solid state relays
- ☐ Converters
- Linear amplifiers
- Constant current sources
- Power supply circuits
- ☐ Telecom

Absolute Maximum Ratings

BV _{DSX}
BV_{DGX}
± 20V
-55°C to +150°C
300°C

^{*} Distance of 1.6 mm from case for 10 seconds.

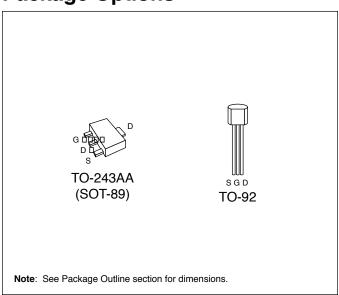
Advanced DMOS Technology

Not recommended for new designs. Please use DN3535 or DN3545 instead.

These depletion-mode (normally-on) transistors utilize an advanced vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Options



12/13/01

Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _A = 25°C	<i>θ</i> _{jc} °C/W	θ _{ja} °C/W	I _{DR} *	I _{DRM}
TO-92	175mA	500mA	0.74W	125	170	175mA	500mA
TO-243AA	200mA	500mA	1.6 [†]	15	78 [†]	200mA	500mA

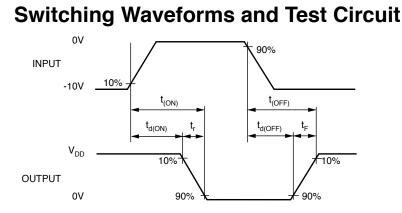
^{*} I_D (continuous) is limited by max rated T_j.

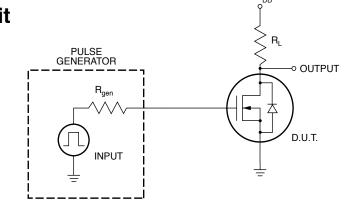
Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter	Min	Тур	Max	Unit	Conditions
BV_{DSX}	Drain-to-Source Breakdown Voltage	300			V	$V_{GS} = -5V, I_D = 100\mu A$
V _{GS(OFF)}	Gate-to-Source OFF Voltage	-1.0		-3.5	V	$V_{DS} = 25V, I_{D} = 10\mu A$
$\Delta V_{GS(OFF)}$	Change in V _{GS(OFF)} with Temperature			4.5	mV/°C	$V_{DS} = 25V, I_{D} = 10\mu A$
I _{GSS}	Gate Body Leakage Current			100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$
I _{D(OFF)}	Drain-to-Source Leakage Current			10	μΑ	V _{GS} = -10V, V _{DS} = Max Rating
				1	mA	$V_{GS} = -10V$, $V_{DS} = 0.8$ Max Rating $T_A = 125$ °C
I _{DSS}	Saturated Drain-to-Source Current	200			mA	$V_{GS} = 0V$, $V_{DS} = 25V$
R _{DS(ON)}	Static Drain-to-Source ON-State Resistance			12	Ω	$V_{GS} = 0V, I_D = 150mA$
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with Temperature			1.1	%/°C	$V_{GS} = 0V, I_D = 150mA$
G _{FS}	Forward Transconductance	300			m ≅ □	I _D = 150mA, V _{DS} = 10V
C _{ISS}	Input Capacitance			300		V _{GS} = -10V, V _{DS} = 25V
C _{OSS}	Common Source Output Capacitance			30	pF	f = 1 MHz
C _{RSS}	Reverse Transfer Capacitance			5		
t _{d(ON)}	Turn-ON Delay Time			10		V _{DD} = 25V,
t _r	Rise Time			15	ns	I _D = 150mA,
t _{d(OFF)}	Turn-OFF Delay Time			15	1	$R_{GEN} = 25\Omega$
t _f	Fall Time			20	1	
V _{SD}	Diode Forward Voltage Drop			1.8	V	V _{GS} = -10V, I _{SD} = 150mA
t _{rr}	Reverse Recovery Time		600		ns	V _{GS} = -10V, I _{SD} = 1A

Notes:

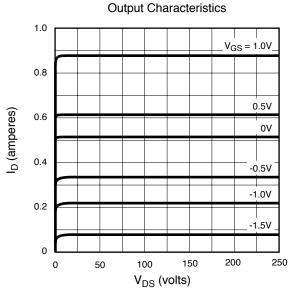
- 1. All D.C. parameters 100% tested at 25°C unless otherwise stated. (Pulse test: 300μs pulse, 2% duty cycle.)
- 2. All A.C. parameters sample tested.

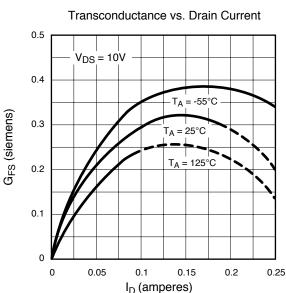


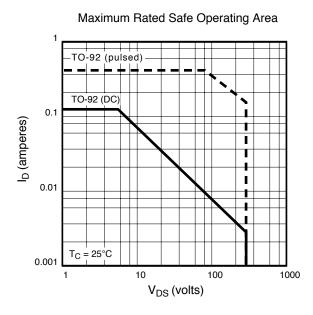


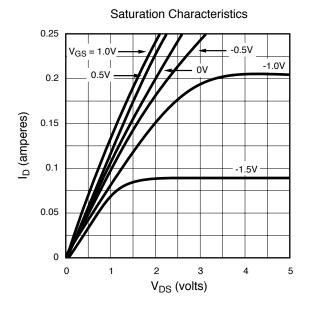
[†] Mounted on FR4 board, 25mm x 25mm x 1.57mm. Significant P_D increase possible on ceramic substrate.

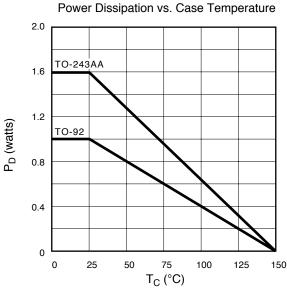
Typical Performance Curves

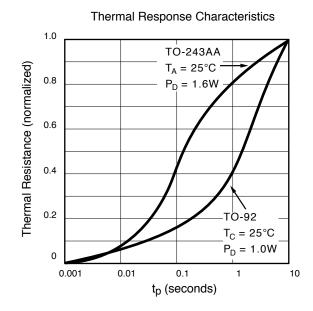












Typical Performance Curves

